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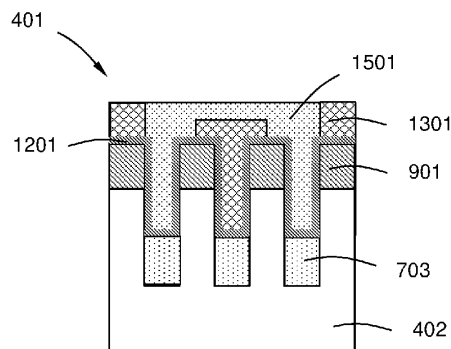
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- (54) **Title:** SELECTIVE DEPOSITION OF CARBON FILMS AND USES THEREOF

FIG. 15



- (57) **Abstract:** Methods of depositing a carbon film are discussed. Some embodiments selectively deposit a carbon film on a metal surface over a dielectric surface. Some embodiments form carbon pillars on metal surfaces selectively over dielectric surfaces. Some embodiments utilize carbon pillars in forming self-aligned vias.



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